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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

AUG 3 1 2004

Applicant(s): Martin R. Handforth

Application No.: 09/821722

Filed: 3/29/2001

Title: Signal Layer Interconnects

Attorney Docket No.: 13888R0US02U 120-042

Group Art Unit:
2827

Conf. No. 4607

Examiner:
NorrisCommissioner for Patents
P.O. Box 1450
Arlington, VA 22313-1450RESPONSE UNDER 37 CFR 1.111

Dear Sir:

Please enter the following Amendment and Remarks in response to the Office Action of July 13, 2004. Kindly amend the claims as shown on the attached sheets.

REMARKS

Claims 1-3, 5, 6, 12, 13 and 29-33 are presented for examination, of which claims 1 and 12 are independent claims. Claims 1-3, 5, 6 and 13 were rejected under 35 U.S.C. 102(b) as being anticipated by Oh. Claims 12 and 29-33 were rejected under 35 U.S.C. 102(b) as being anticipated by Sugimoto. Claims 5 and 6 are currently amended. Reconsideration is requested.

Claim 1 distinguishes Oh by reciting that "at least one conductive protrusion is formed on said conductive inner layer trace." The Office suggests that Oh teaches conductive protrusions with element (142). However, elements (142) of Oh are merely connecting pads which have been known in the art for some considerable time. As stated in Oh, "a plurality of connecting